

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-10 (Canceled)

11. (New) A power module device, comprising:

a first heat sink having at least one hole;

at least one second heat sink being fitted in a respective one of said at least one hole and having an expansion coefficient smaller than an expansion coefficient of said first heat sink;

a semiconductor component fixed by solder to a surface of said second heat sink; and

a plastic flow portion stress-bonded for close adhesion to an outer peripheral surface of said second heat sink, said plastic flow portion being material of said first heat sink;

wherein a recessed-shaped pressing mark is defined by a surface of said first heat sink and an outer peripheral surface of said second heat sink.

12. (New) The power module device according to Claim 11, wherein said second heat sink has a disk or elliptic shape.

13. (New) The power module device according to Claim 12, wherein a part of the peripheral surface of said heat sink is exposed at said pressing mark having recess shape recessed to the plastic flow bonding.

14. (New) The power module device according to Claim 11, wherein a semiconductor chip is fixed on a surface of said second heat sink.

15. (New) The power module device according to Claim 14, wherein a width of said pressing mark is relatively small, said pressing mark being formed around said second heat sink.

16. (New) A power module device, comprising:

a first heat sink having at least one hole and being made of a Cu-based material;

at least one second heat sink being fitted in a respective one of said at least one hole and made of a Cu-Mo composition material having an expansion coefficient smaller than an expansion coefficient of said first heat sink;

a semiconductor component fixed to one surface of said second heat sink by solder; and

a plastic flow portion stress-bonded for close adhesion to an outer peripheral surface of said second heat sink, said plastic flow portion being material of said first heat sink;

wherein a recess-shaped pressing mark is defined by a surface of said first heat sink, and outer peripheral surface of said second heat sink.

17. (New) The power module device according to Claim 16, wherein said second heat sink has a disk or elliptic shape.

18. (New) The power module device according to Claim 17, wherein a part of the peripheral surface of said heat sink is exposed at said pressing mark having recess shape recessed to the plastic flow bonding.

19. (New) The power module device according to Claim 16, wherein a semiconductor chip is fixed on a surface of said second heat sink.

20. (New) The power module device according to Claim 19, wherein a width of said pressing mark is relatively small, said pressing mark being formed around said second heat sink.